

# MIL-T-10727

REVISION C  
6/30/1989  
TIN PLATING: ELECTRODEPOSITED  
OR HOT-DIPPED, FOR FERROUS AND  
NONFERROUS METALS



THIS SPECIFICATION COVERS THE REQUIREMENTS FOR ELECTRODEPOSITED TIN AND HOT-DIPPED TIN COATINGS ON FERROUS AND NONFERROUS METALS.

| <u>MIL-T-10727 DEPARTURES</u> | <u>EFF DATE</u> | <u>SUBCONTRACTOR(S) AFFECTED</u> | <u>ON MODELS</u> | <u>MFG DEPTS OF DIV BELOW AFFECTED</u> | <u>REASON</u>  |
|-------------------------------|-----------------|----------------------------------|------------------|--|--|
| NOTICE 1                      | 2/7/1997        | ALL                              |                  |  | MIL-T- 10727C, DATED 30 JUNE 1989, IS HEREBY CANCELED. FUTURE REQUIREMENTS FOR TIN PLATING ELECTRODEPOSITED (TYPE 1) SHOULD REFER TO ASTM B 545, "STANDARD SPECIFICATION FOR ELECTRODEPOSITED COATINGS OF TIN", (DOD ADOPTED). FUTURE REQUIREMENTS FOR TIN FOR USE IN HOT-DIPPED APPLICATIONS (TYPE H) SHOULD REFER TO ASTM B 339, "TIN, PIG", GRADE A, (DOD ADOPTED). |